



BRIGHTTEK
BRIGHTTEK (EUROPE) LIMITED

Brighten Up The World With LED!



ISO/TS 16949:2009



BS EN ISO 14001:2004



QC 080000 IECQ HSPM

PRODUCT DATASHEET

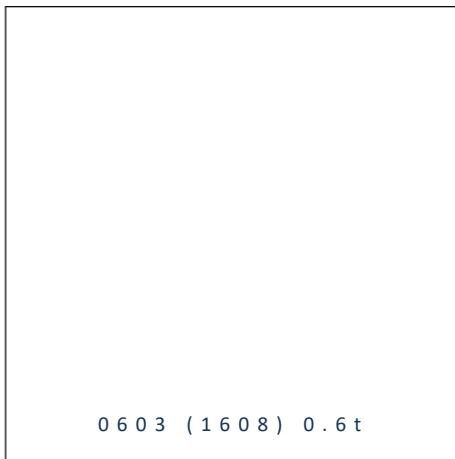


- ▶ CHIP / PCB SMD
- ▶ 0603 (1608) 0.6t
- ▶ Cool White 6700K

NOW07S12



Release Date: 05 January 2024 Version: A1.2



0603 (1608) 0.6t

0603 (1608) 0.6t



FEATURES:

- **Package:** Top View CHIP SMD Package
- **Forward Current:** 20mA
- **Forward Voltage (typ.):** 3.2V
- **Luminous Intensity (typ.):** 450mcd@20mA
- **Colour:** Cool White
- **Colour Temperature (CCT):** 5400~9800K
- **Viewing Angle:** 140°
- **Materials:**
 - Die: InGaN
 - Resin: Silicon (Yellow Diffused)
 - L/T Finish: Au plated
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+100°C
- **Grouping Parameters:**
 - Forward Voltage
 - Luminous Intensity
 - CIE Chromaticity
- **Soldering Methods:** Reflow Soldering
- **MSL Level:** according to JEDEC MSL 2a
- **Packing:** 8mm tape with max.4000/reel, ø180mm (7")

APPLICATIONS:

- Backlighting
- Consumer Goods
- Indicators
- Torch Lights
- Toy Lights
- Decorating Lights

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	I _F	30	mA
Pulse Forward Current @Duty 1/10, 0.1ms	I _{PF}	100	mA
Power Dissipation	P _d	100	mW
Reverse Voltage	V _R	5	V
Reverse Current @10V	I _R	10	μA
Junction Temperature	T _j	110	°C
Electrostatic Discharge (HBM)	ESD	1000	V
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C
Soldering Temperature	T _{SOL}	260	°C

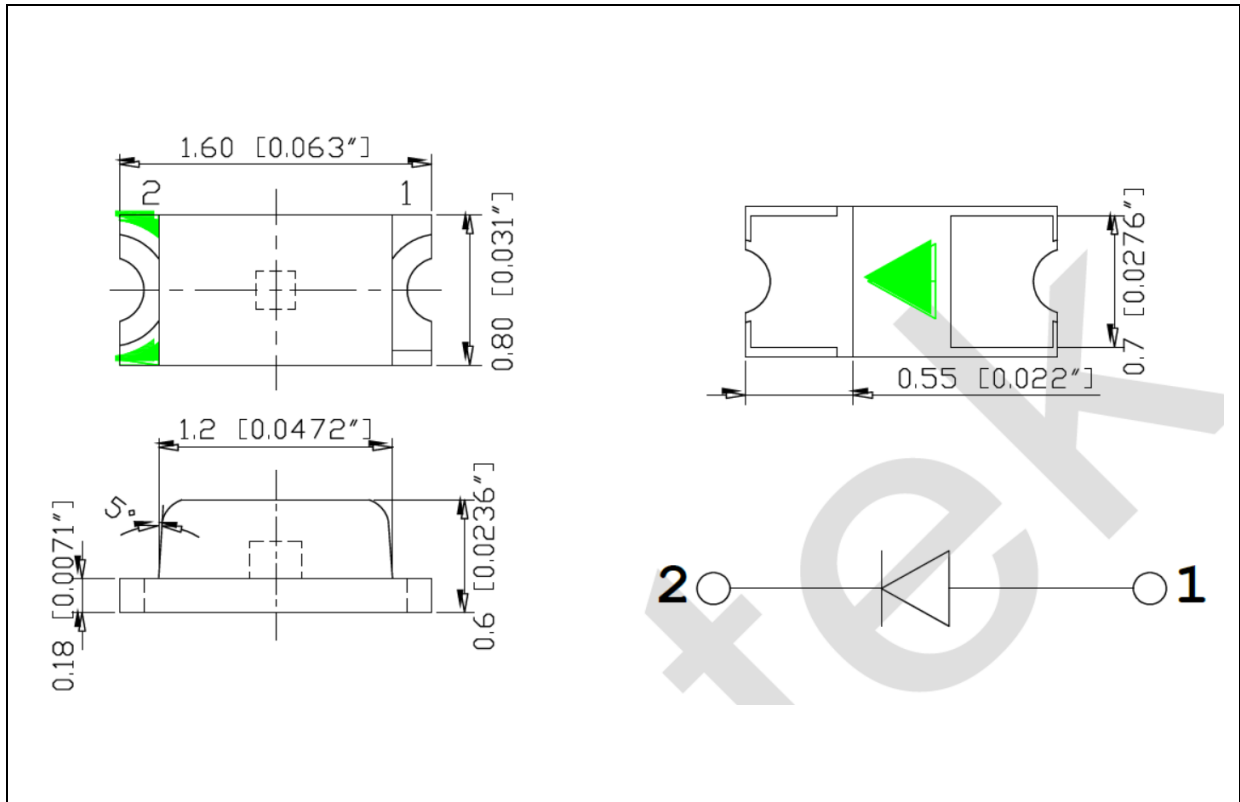
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V _F	2.8	---	3.7	V	I _F =20mA
Luminous Intensity	I _v	250	450	---	mcd	I _F =20mA
Chromaticity Coordinates	X	---	0.3098	---	---	I _F =20mA
	Y	---	0.3145	---		
Colour Temperature	CCT	---	6700	---	K	I _F =20mA
Viewing Angle	2θ _{1/2}	---	140	---	deg	I _F =20mA

1. Luminous Intensity (Φ_v) ±10%, Forward Voltage (V_F) ±0.1V, Colour Coordinate: ±0.005, Viewing Angle(2θ_{1/2}) ±5%

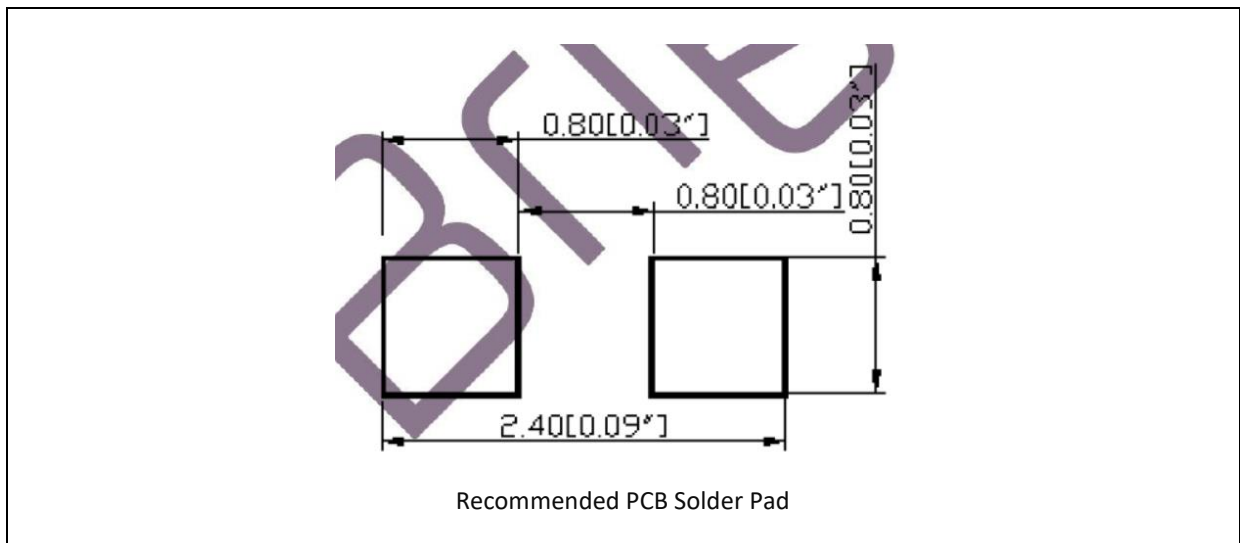
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance ± 0.13 mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



1. Dimensions are in millimetre (mm).
2. Tolerance ± 0.1 mm with angle tolerance $\pm 0.5^\circ$.

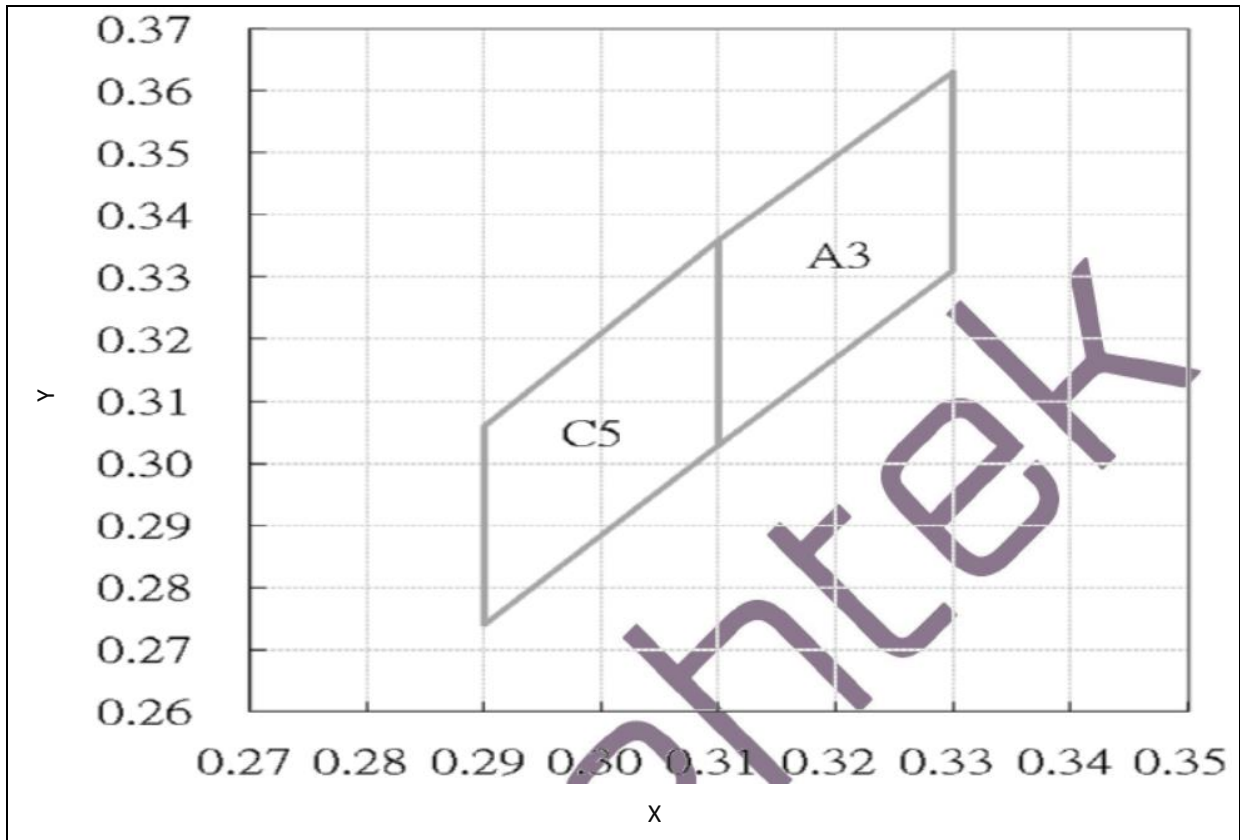
BINNING GROUPS:

 Forward Voltage Classifications ($I_F = 20\text{mA}$):

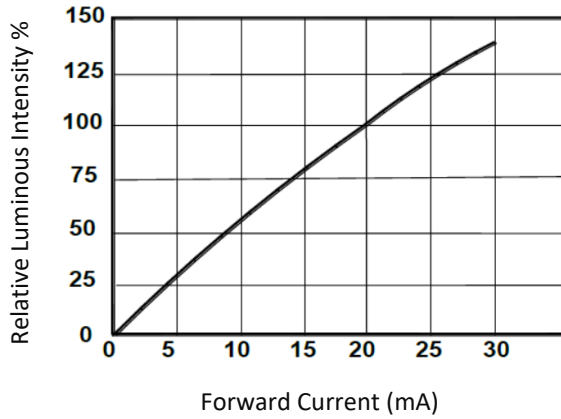
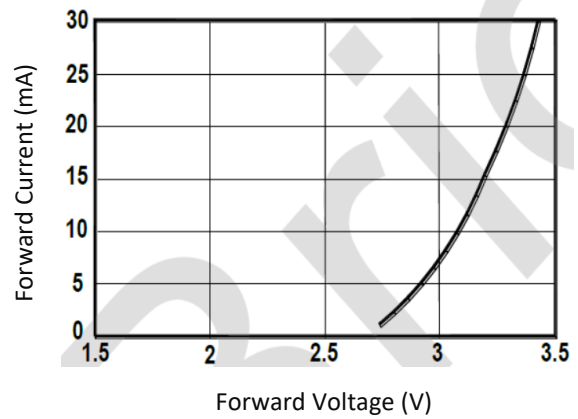
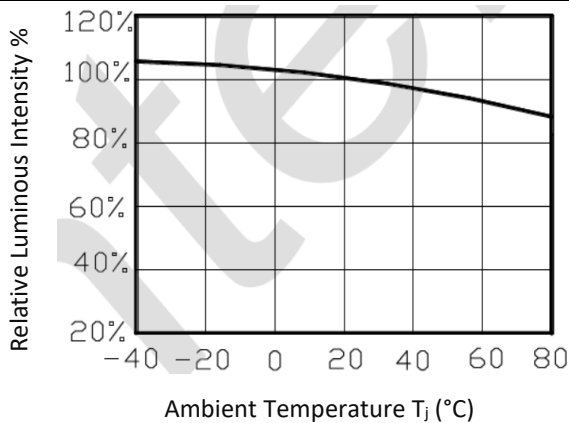
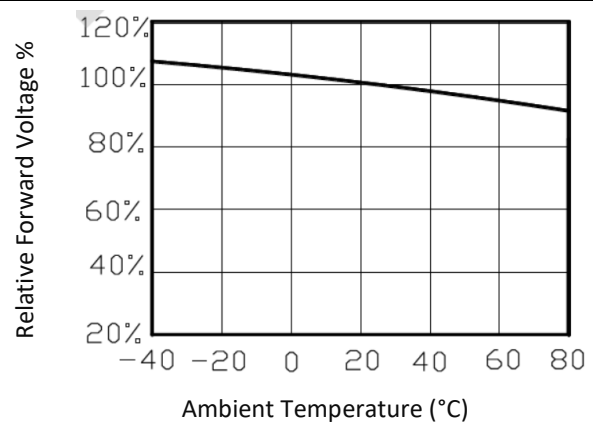
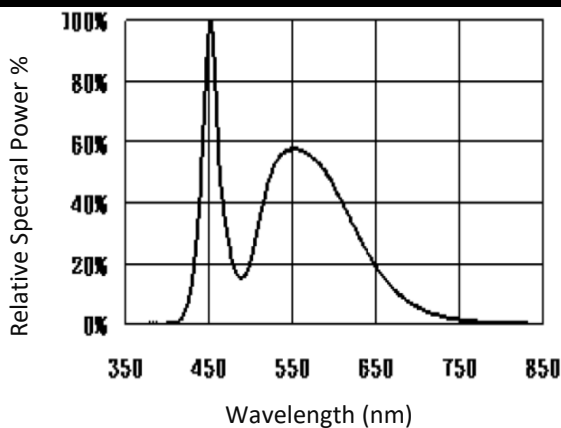
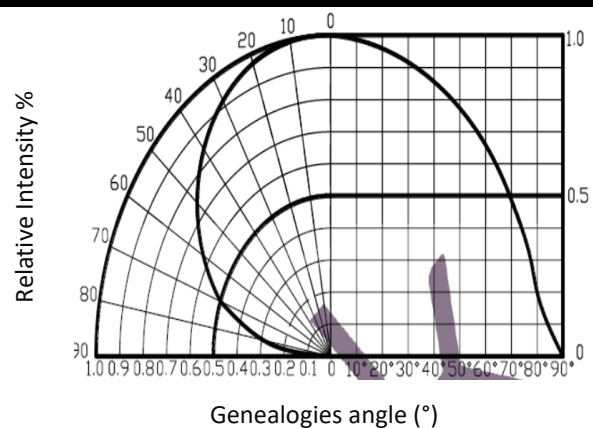
Code	Min.	Max.	Unit
f	2.8	3.1	V
g	3.1	3.4	
h	3.4	3.7	

 Luminous Intensity Classifications ($I_F = 20\text{mA}$):

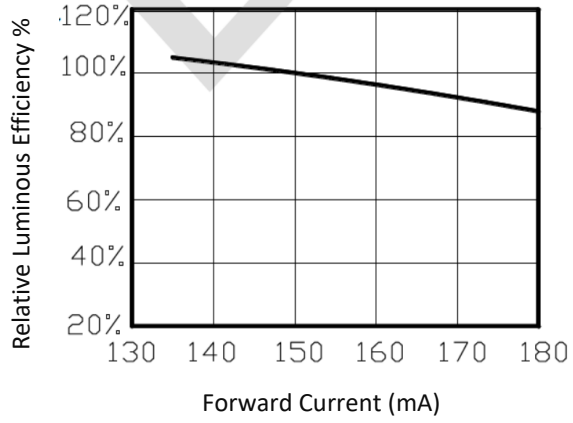
Code	Min.	Max.	Unit
N	250	320	mcd
O	320	400	
P	400	500	
Q	500	630	

CIE CHROMATICITY DIAGRAM:

 Chromaticity Coordinates Classifications ($I_F = 20\text{mA}$):

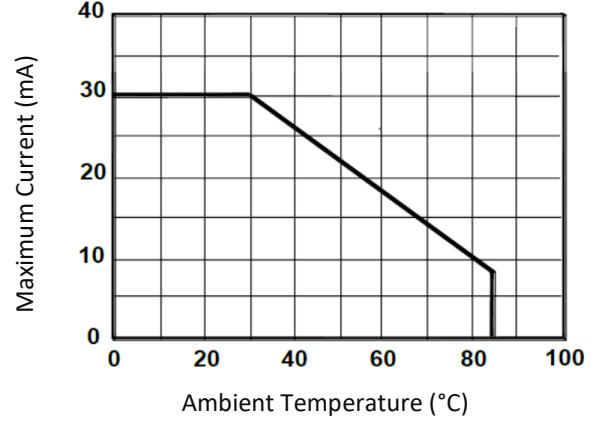
	1		2		3		4	
	x	y	x	y	x	y	x	y
C5	0.3100	0.3360	0.2900	0.3060	0.2900	0.2740	0.3100	0.3030
A3	0.3300	0.3630	0.3100	0.3360	0.3100	0.3030	0.3300	0.3310

ELECTRO-OPTICAL CHARACTERISTICS:
Relative Luminous Intensity v.s. Forward Current

Forward Current v.s. Forward Voltage

Relative Luminous Intensity v.s. Ambient Temp.

Relative Forward Voltage v.s. Ambient Temp.

Relative Spectral Power v.s. Wavelength

Directive Radiation


Relative Emission Efficiency v.s. Forward Current

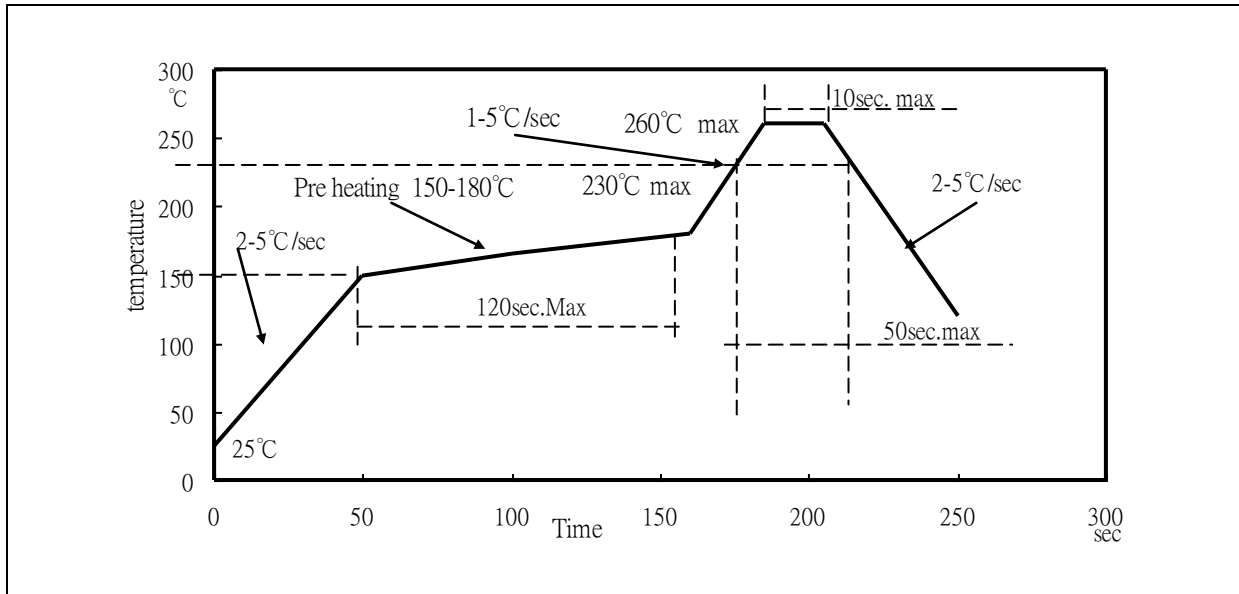


Forward Current Derating Curve



RECOMMENDED SOLDERING PROFILE:

IR Reflow Lead-free Solder:

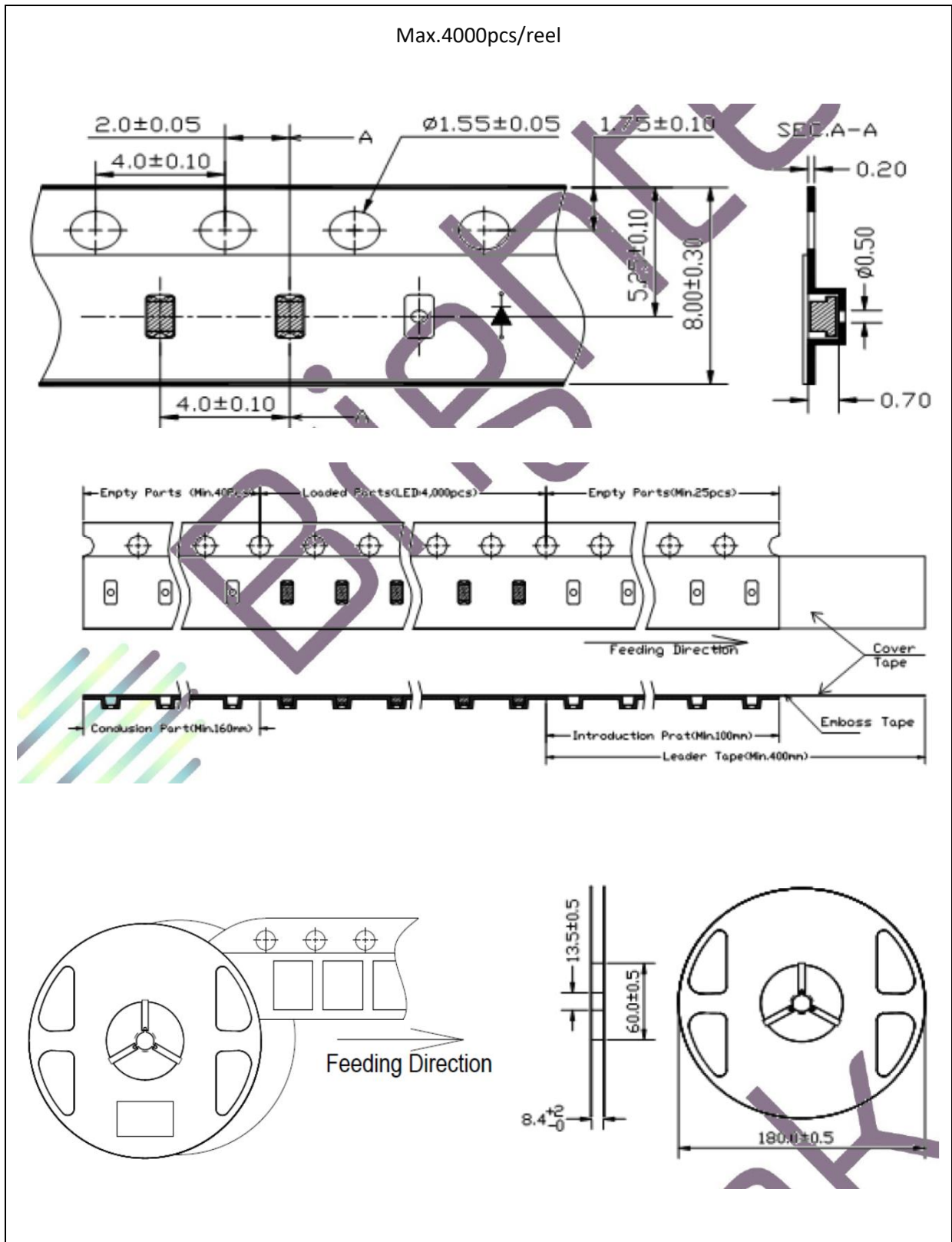


Note:

1. Recommended soldering temperature: 240°C. The maximum soldering temperature should be limited to 260°C.
2. Maxima reflow soldering: 3 times.
3. Before, during, and after soldering, should not apply stress on the components and PCB board.

PACKING SPECIFICATION:

Reel Dimension:



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with desiccating agent <10% R.H. and apply baking.

Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handling the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	20/05/2016	Datasheet set-up.
A1.1	26/05/2022	New datasheet format.
A1.2	05/01/2024	Revise MSL level and CCT bin range.